O를 선도하는

우리는 10 년 이상의 경험을 가진 전문 PCB 제조업체입니다. 제품 범위 : 단일, 양면, 다층 PCB, 유연한 PCB 및 MCPCB. 우리는 빠른 프로토 타입 서비스를 제공 할 수 있습니다 : 24 시간 안에 S / S, 48-96 시간 생산에 4-8 대.
(무거운_구리_도자기_제조업체)

구리판 구멍 최소 .025 AVG, .020 분 .. 구멍을 연결할 수 없음

무색 투명 버블 필름 패키지, 25 개 / 가방, 건조제를 측면에 놓고 습도 표시기 보드를 상단에 놓습니다.

자세한 정보는 여기를 클릭하십시오 :

제품 설명

PCB P / N	LE-150
레이어 계산	1L
재료	기본 도자기
이사회	3.2 mm
구리의 thk	1 온스
가장 작은 구멍 크기	/
구멍 수 (개)	/
라인 승 / s	/
S / N 임피던스 점검 (Tol %)	엔
표면 마무리	ENIG (Au : 0.05um)
실크 스크린 용접 마스크	검정, 흰색
단일 치수	희미한 X (mm) : 27; 희미한 Y (mm) : 45
패널화	희미한 X (mm) : 27; 희미한 Y (mm) : 135; UPS 번호 : 3
스페셜 : 필러 블 마스크	엔
라우팅 / 펀칭	카운터 싱크 CNC 스크류 +

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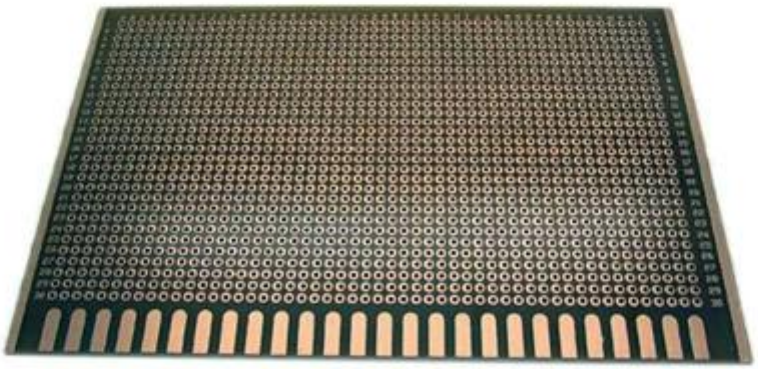
O-LEADING
To Be Reliable, To Be Valuable



www.o-leading.com

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O-LEADING
To Be Reliable, To Be Valuable

Quality Management System Certificate

This is to certify that
(Organization Code Certificate : 61691591-000-07-16-8)

O-LEADING SUPPLY CHAIN (HK) CO.,LIMITED

ROOM 603D, 6/F HANG PONT COMMERCIAL BUILDING, 31 TONKIN ST., CHEUNG SHA WAN, KL, HK

has been established the quality management system meeting the requirements of standard

GB/T19001-2008/ISO9001:2008

Scope:

Certification Address: Room 1313, Fortune Building, Nanheng West Road, Huiyang District, Huizhou, Guangdong, China

Certification Activities: Sales and services of printed circuit boards

Certificate No.: 51816Q01163R0S

Issued Date : 2016-11-17 **Valid to :** 2018-09-15

Initial Issued Date : 2016-11-17 **Renewal Date :** ***

GM

CICC INSPECTION CERTIFICATION

CIGG CERTIFICATION
嘉泰认证

QUALITY MANAGEMENT SYSTEM CERTIFICATE

Certificate No: 18118Q10347R0S

We hereby certify that

O-LEADING SUPPLY CHAIN(HK) CO.,LIMITED

Credit No: 61691591-000-07-17-2

Registration Add:ROOM 603D,6/F HANG PONT COMMERCIAL BUILDING,31 TONKIN ST,CHEUNG SHA WAN,KL,HK

Business Add:1313,Floor 13,Fortune Building,Danshui Town,Huiyang District, Huizhou,Guangdong,China

Has implemented and maintains a **Quality Management System**

Which fulfils the requirements of the following standards

GB/T19001-2016 idt ISO9001:2015

Scope of certification

Sales of printed circuit boards

Initial Issuance period: February 27, 2018

This certificate is valid during: February 27, 2018 — February 26, 2021

This certificate is invalid without CICC qualified label in the following period

First supervision and audit	Qualified mark	Second supervision and audit	Qualified mark

CICC IAF CNAS

2017/2/6 ZPMV2.E490354 - Wiring, Printed - Component

UL ONLINE CERTIFICATIONS DIRECTORY

ZPMV2.E490354
Wiring, Printed - Component

For enhanced search functionality, please visit UL's iQ™ Family of Databases.
Click on a product designation for complete information.

Page Bottom

Wiring, Printed - Component

See General Information for Wiring, Printed - Component

O-LEADING SUPPLY CHAIN CO LIMITED E490354
Fortune Building, Nanheng West Road
Room 1313
Huizhou, Guangdong 516211, CHINA

	Cond Width				Max			Max			
		Min	Cond	SS/	Area	Solder		Oper		Meets	C
	Min	Edge	Thk	DS/	Diam	Limits		Temp	Flame	UL796	T
Type	mm(in)	mm(in)	mic(mil)	DSO	mm(in)	C	sec	C	Class	DSR	I
Multilayer (mass laminate) printed wiring boards.											
O-LEADING-401											
	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	-	-
O-LEADING-407											
	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All	-
Multilayer printed wiring boards.											
O-LEADING-408											
	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:135	DS	50.8 (2.0)	260	20	130	V-0	All	*
Single layer printed wiring boards.											
O-LEADING-002											
	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All	-
O-LEADING-003											
	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	▲	-
O-LEADING-033											
	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All	-
O-LEADING-205											
	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING-206											
	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All	-

* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.
Last Updated on 2017-01-27

Questions? Print this page Terms of Use Page Top

http://database.ul.com/cgi-bin/XYV/template/LISEXT/1FRAME/showpage.html?name=ZPMV2.E490354&ccnumber=Wiring,+Printed+-+Component&original... 1/2

SGS

Test Report No. CANEC1805164701 Date: 03 Apr 2018 Page 2 of 6

Test Results :

Test Part Description :

Specimen No.	SGS Sample ID	Description
SN1	CAN18-051647.001	Green "PCB"

Remarks :

(1) 1 mg/kg = 1 ppm = 0.0001%
(2) MDL = Method Detection Limit
(3) ND = Not Detected (< MDL)
(4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC62321-5:2013, IEC62321-7-2:2017 , IEC 62321-6:2015 and IEC62321-8:2017, analyzed by ICP-OES , UV-Vis and GC-MS .

Test Item(s)	Limit	Unit	MDL	001
Cadmium (Cd)	100	mg/kg	2	ND
Lead (Pb)	1,000	mg/kg	2	9
Mercury (Hg)	1,000	mg/kg	2	ND
Hexavalent Chromium (CrVI)	1,000	mg/kg	8	ND
Sum of PBBs	1,000	mg/kg	-	ND
Monobromobiphenyl	-	mg/kg	5	ND
Dibromobiphenyl	-	mg/kg	5	ND
Tribromobiphenyl	-	mg/kg	5	ND
Tetrabromobiphenyl	-	mg/kg	5	ND
Pentabromobiphenyl	-	mg/kg	5	ND
Hexabromobiphenyl	-	mg/kg	5	ND
Heptabromobiphenyl	-	mg/kg	5	ND
Octabromobiphenyl	-	mg/kg	5	ND
Nonabromobiphenyl	-	mg/kg	5	ND
Decabromobiphenyl	-	mg/kg	5	ND
Sum of PBDEs	1,000	mg/kg	-	ND
Monobromodiphenyl ether	-	mg/kg	5	ND
Dibromodiphenyl ether	-	mg/kg	5	ND
Tribromodiphenyl ether	-	mg/kg	5	ND
Tetrabromodiphenyl ether	-	mg/kg	5	ND
Pentabromodiphenyl ether	-	mg/kg	5	ND

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1. O-Leading□ □□□ □□□ □□□□□?
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1. □□□□□ ISO 9001 : 2008 □□□ □□ □□□□ □□□□□.
2. □□ □□ □□□□ □□□□□□ □□□□ □□
3. □□□ □□□ □□ □ □□. □□ □□. □□□ □□□, X-ray □□, AOI (Automated Optical Inspector) □ ICT (in-circuit test).
4. □□ □□ □□ □□□□□ □□ □□□ □□ □□ □
5. □□ □□ □ □□□□ □□

2. O-Leading□ □□□ □□□□□ □□□ □□□□□?
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3. O-Leading 프로세스는 어떤 유형의 카드를 사용할 수 있습니까?
FR4 공통, 고 TG 및 무 할로겐 보드, Rogers, Arlon, Telfon, 알루미늄 / 구리 보드, PI 등

4. PCB 생산에 필요한 데이터는 무엇입니까?
Gerber 274-X 형식으로 데이터를 제공하는 것이 좋습니다. 또한 Cam350, CAD, Protel 99se, PADS, DXP 및 Eagle도 처리 할 수 있습니다.

5. 다층 PCB의 일반적인 프로세스 흐름은 무엇입니까?
절단 재료 → 내부 드라이 필름 → 내부 에칭 → 내부 AOI → 멀티 본드 → 레이어 오버 랩핑 압착 → 드릴링 → PTH → 도금 → 외부 드라이 필름 → 도금 → 외부 조각 → 외부 AOI → 용접 마스크 → 구성 요소 마크 → 마감 표면 → 라우팅 → E / T → 육안 검사.